# **MA26V11**

## Silicon epitaxial planar type

### For VCO

#### Features

 $\bullet$  Good linearity and large capacitance-ratio in  $C_D$  –  $V_R$  relation

T<sub>stg</sub>

-55 to +125

 $\bullet$  Small series resistance  $r_{\rm D}$ 

Parameter

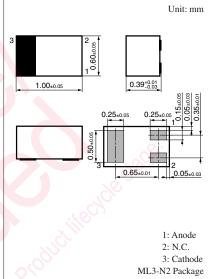
Reverse voltage

Junction temperature

Storage temperature

• High frequency type by this low capacitance

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$ Symbol Rating Unit V<sub>R</sub> 8 V 125 $T_j$ °C °C



Marking Symbol: 2L

## Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Reverse current		IR	$V_R = 5 V$	00	cOr.	10	nA
Diode capacitance		C <sub>D1V</sub>	$V_R = 1 V, f = 1 MHz$	2.77	0-	3.01	pF
		C <sub>D4V</sub>	$V_R = 4 V, f = 1 MHz$	1.23		1.34	
Capacitance ratio		C <sub>D1V</sub> /C <sub>D4V</sub>		2.16		2.34	—
Series resistance *	20	r <sub>D</sub>	$V_{\rm R} = 4 \text{ V}, \text{ f} = 470 \text{ MHz}$			0.35	Ω

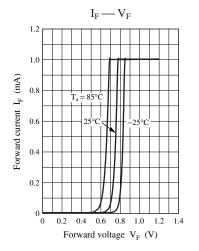
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

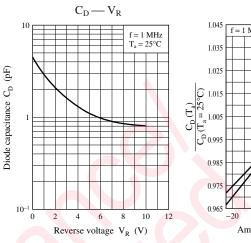
2. Absolute frequency of input and output is 470 MHz.

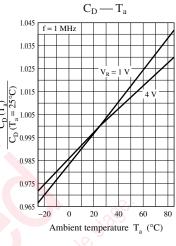
3. \*: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

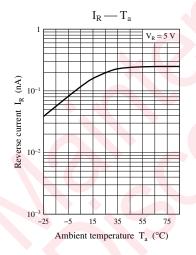
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